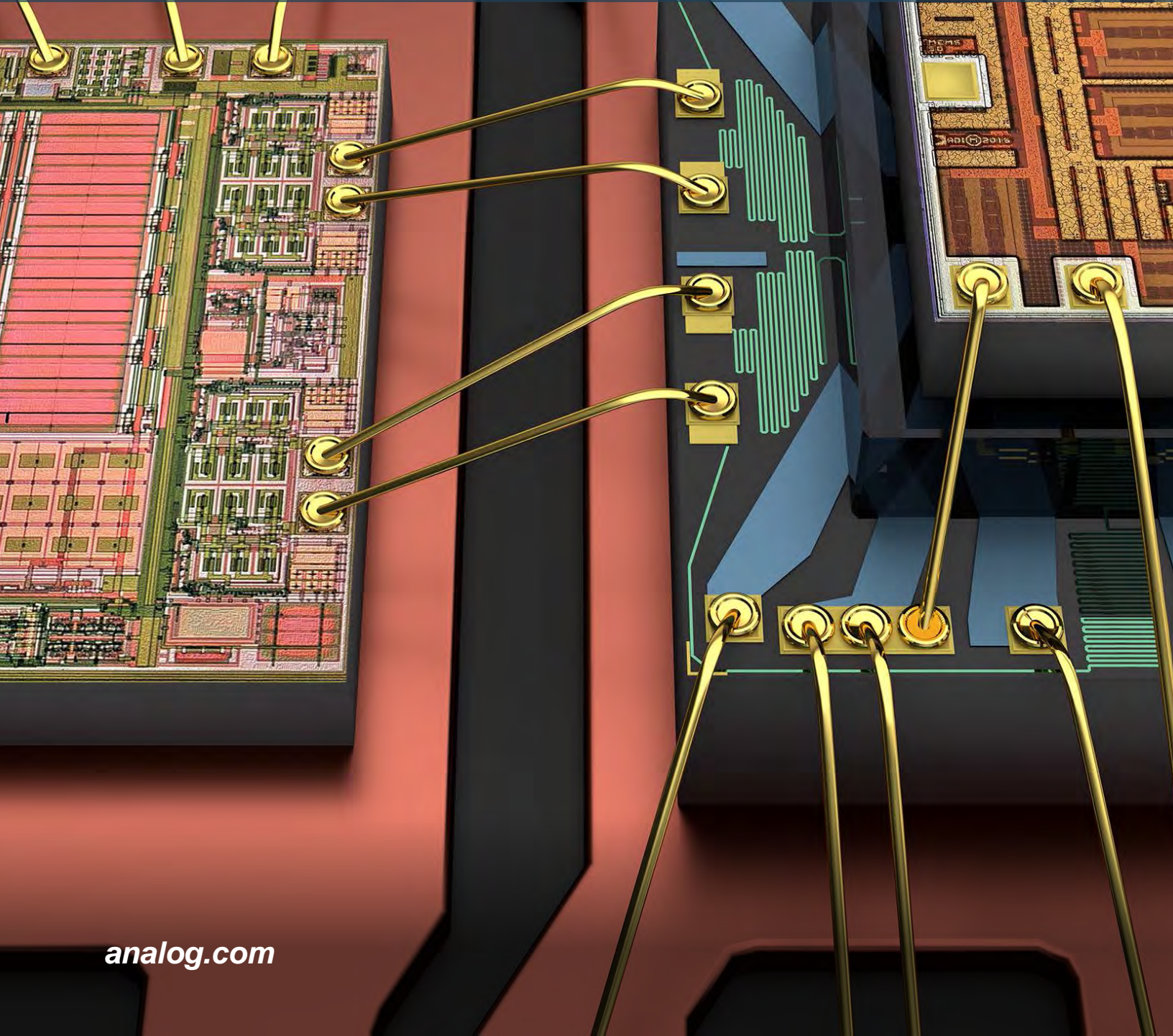


RELIABILITY REPORT





Reliability Data Report Product Family R378

LT1797 / LT1800 / LT1801 / LT1802 / LT1803 /
LT1804 / LT1805 / LT1806 / LT1807 / LT1809 /
LT1812 / LT1810 / LT1813 / LT1814 / LT1815 /
LT1816 / LT1817 / LT1818 / LT1969 / LT6200 /
LT1819 / LT6201 / LT6202 / LT6203 / LT6204 /
LT6205 / LT6206 / LT6207 / LT6210 / LT6220 /
LT6221 / LT6230 / LT6231 / LT6232 / LT6233 /
LT6234 / LT6235 / LT6236 / LT6237 / LT6238 /
LT6350 / LT6411 / LT6550

Reliability Data Report

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OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES ^{2, 3}
SSOP/TSSOP	231	0421	0533	231	0
SOIC/MSOP	4010	9914	1348	3760	0
PLASTIC DIP	77	0630	0630	77	0
QFN/DFN	77	0630	0630	77	0
FLATPACK	157	0414	1051	84	0
Totals	4,552	-	-	4,229	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	2221	0231	1349	153	0
SSOP/TSSOP	1603	0205	1402	163	0
SOIC/MSOP	23840	9905	1420	2805	0
Totals	27,664	-	-	3,121	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	2073	0231	1349	448	0
SSOP/TSSOP	1081	0205	1402	445	0
SOIC/MSOP	18219	9905	1419	6073	0
FLATPACK	17	0414	0414	1	0
Totals	21,390	-	-	6,967	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	2005	0231	1349	319	0
SSOP/TSSOP	1270	0205	1402	373	0
SOIC/MSOP	17850	9905	1419	5429	0
FLATPACK	17	0414	0414	0	0
Totals	21,142	-	-	6,121	0

HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SSOP/TSSOP	80	0820	0829	80	0
SOIC/MSOP	698	0751	0910	688	0
QFN/DFN	100	0851	1349	100	0
Totals	878	-	-	868	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.43 FITS

(3) Mean Time Between Failure in Years = 263344.47

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/MSOP	200	1325	1402	200	0
Totals	200	-	-	200	0